

注記
NOTES:

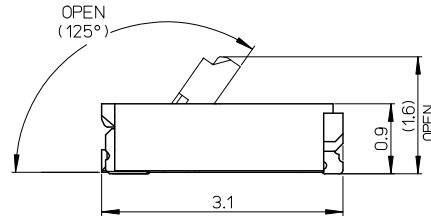
1.材質

MATERIAL

ハウジング:LCP(液晶ポリマー)、ガラス充填、UL94V-0
 HOUSING:LCP(LIQUID CRYSTAL POLYMER),
 GLASS FILLED,UL94V-0
 アクチュエータ:ナイロン、ガラス充填、UL94V-0
 ACTUATOR:NYLON(POLYAMIDE),
 GLASS FILLED,UL94V-0
 ターミナル:銅合金(t=0.15)
 TERMINAL:COPPER ALLOY(t=0.15)
 金具:銅合金(t=0.15)
 NAIL:COPPER ALLOY(t=0.15)

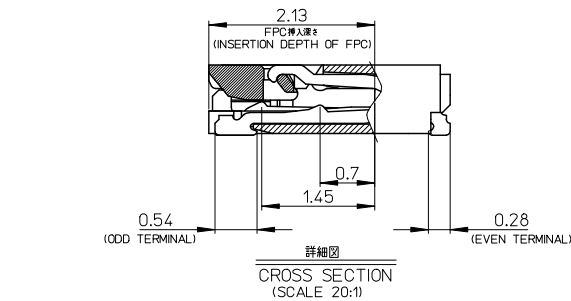
2.めっき仕様
PLATING

ターミナル
TERMINAL
部分金めっき
SEPARATED GOLD PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
金具
NAIL
めっき
TIN PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



0.10	16.15	14.4	15	17.4	501628-5191	51
0.089	14.35	12.6	13.2	15.6	501628-4591	45
0.078	12.55	10.8	11.4	13.8	501628-3991	39
0.075	11.95	10.2	10.8	13.2	501628-3791	37
0.071	11.35	9.6	10.2	12.6	501628-3591	35
0.067	10.75	9.0	9.6	12.0	501628-3391	33
0.064	10.15	8.4	9	11.4	501628-3191	31
0.056	8.95	7.2	7.8	10.2	501628-2791	27
0.046	7.15	5.4	6	8.4	501628-2191	21
0.028	4.15	2.4	3	5.4	501628-1191	11
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER No.	極数 CIRCUITS

CONNECTOR SERIES No. 501628-xx11

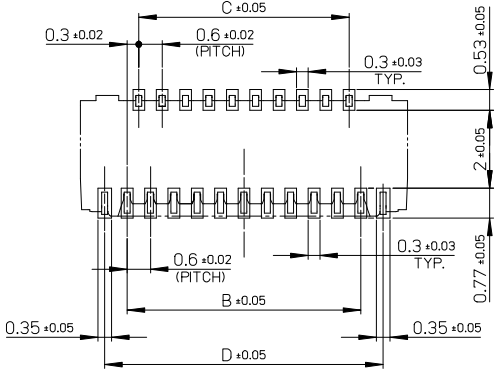


REVISED
 E.C. NO: J2010-0068
 DRAWN BY: DRINKUSATO 2009/07/30
 CHECKED BY: CHYKOSHINOYAMA 2009/07/31
 APPROVED BY: KIMORI KAWA 2009/07/31

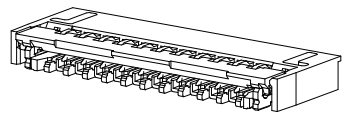
GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±1 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	SCALE 40:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY HSHIMUYAMA	DATE 2005/03/25	TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER	
CHECKED BY HHIRATA	DATE 2005/03/25	MOLEX INCORPORATED	
APPROVED BY MSASAO	DATE 2005/03/25	DOCUMENT NO. SD-501628-001	SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

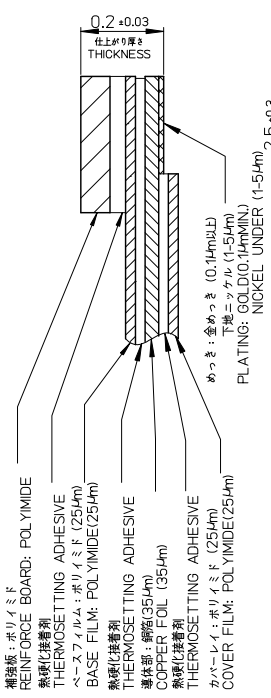
10 9 8 7 6 5 4 3 2 1



推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT
(SCALE 5:1)

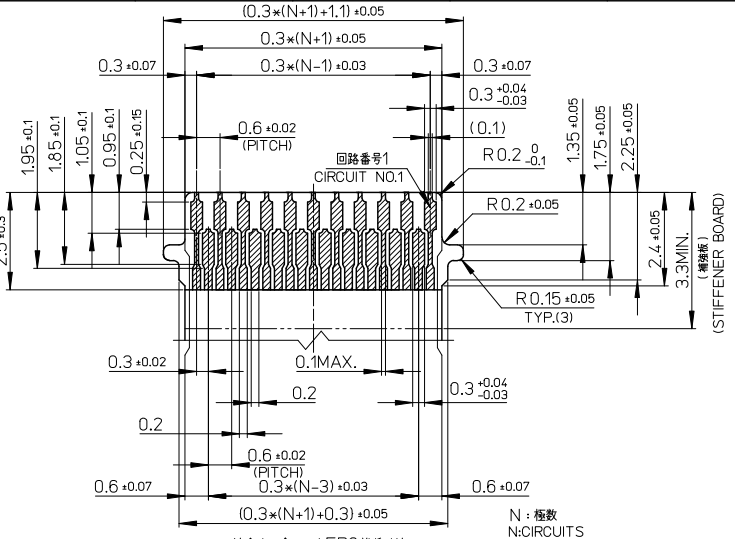


ISO VIEW (参考)



- 補強板: ポリイミド REINFORCE BOARD: POLYIMIDE
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- ベースフィルム: ポリイミド (25µm) BASE FILM: POLYIMIDE (25µm)
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- 導体部: 銅箔 (35µm) COPPER FOIL (35µm)
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- カバーフィルム: ポリイミド (25µm) COVER FILM: POLYIMIDE (25µm)

FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

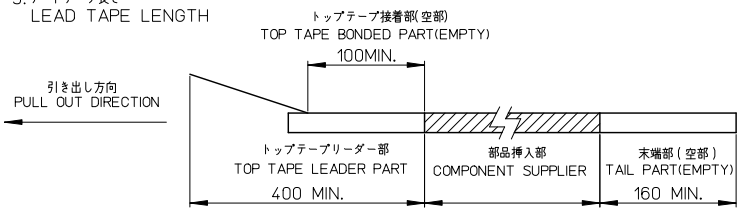
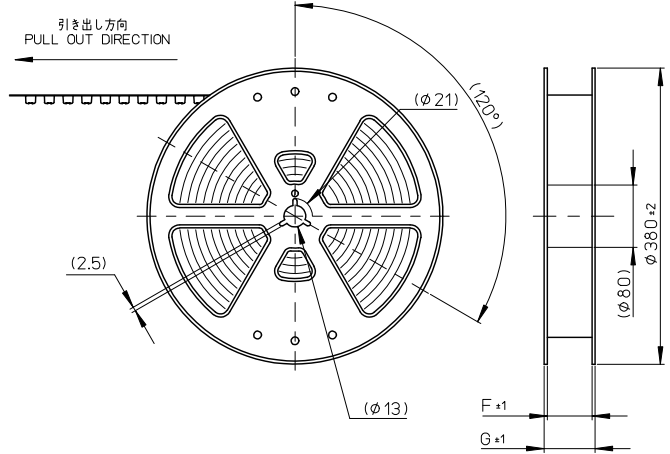
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE
CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE
THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2010-0068 DRAWN BY: DRINKUSATO 2009/07/30 CHECKED BY: CHYKOSHINOYAMA 2009/07/31 APPROVED BY: KNOBIKAWA 2009/07/31 DESCRIPTION REVISION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 40:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY: HSHIMOYAMA 2005/03/25	DATE: 2005/03/25	TITLE	0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER
	10 OVER 30 UNDER	± 0.25	CHECKED BY: HHIRATA 2005/03/25	DATE: 2005/03/25		
	30 OVER	± 0.3	APPROVED BY: MSASAO 2005/03/25	DATE: 2005/03/25	MATERIAL NO.	DOCUMENT NO.
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SD-501628-001	2 OF 2	

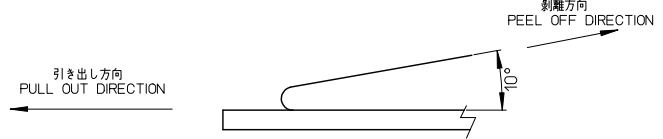
10 9 8 7 6 5 4 3 2 1

注記)
NOTES

- 1.製品番号501628-***11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 501628-***11 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
- 2.梱包数量:3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- 3.リードテープ長さ
LEAD TAPE LENGTH



- 4.トップテープの剥離強度 (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
0.1-1.3N (10-130gf)
尚、本規格値は出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しないこと)
(PEEL OFF SHOULD NOT BE ALLOWED DURING TRANSPORTATION.)

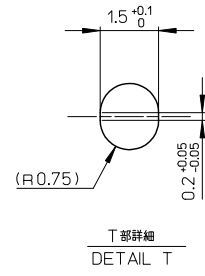
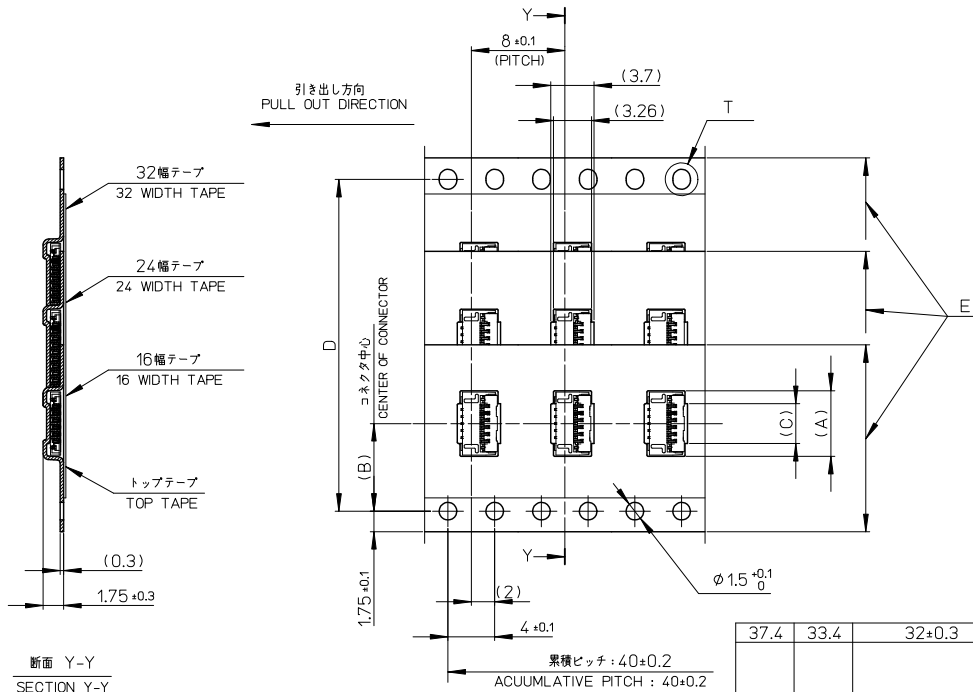


- 5.材料
MATERIAL
キャリアテープ:ポリスチレン (PS)
CARRIER TAPE:POLYSTYRENE (PS)
トップテープ:PET,PE,PEF
TOP TAPE :PET,PE,PEF
リール:ポリスチレン
REEL:POLYSTYLENE

- 6.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2010-0068 DRAWN BY: DRWNGUSATO 2009/07/30 CHECKED BY: CHYKOSHINOYAMA 2009/07/31 APPROVED BY: KIMORI KAWA 2009/07/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY HSHIMOYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628-***11) TAPING PACKAGE NICKEL BARRIER	
	10 OVER 30 UNDER	± ---	CHECKED BY HHIRATA	DATE 2005/08/22	MOLEX INCORPORATED	
	30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501628-003
DESCRIPTION	ANGULAR ± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



37.4	33.4	32±0.3	28.4	15.4	14.2	17.6	501628-5191	51
29.4	25.4	24±0.3	±	13.6	11.5	15.8	501628-4591	45
				11.8		14	501628-3991	39
				11.2		13.4	501628-3791	37
				10.6		12.8	501628-3591	35
				10.0		12.2	501628-3391	33
21.4	17.4	16±0.3		9.4	7.5	11.6	501628-3191	31
				8.2		10.4	501628-2791	27
				6.4		8.6	501628-2191	21
G	F	E	D	C	B	A	製品番号	極数
		EMBOSSED TAPE WIDTH					MATERIAL NO.	CIRCUITS

断面 Y-Y
SECTION Y-Y

REVISED IEC NO: J2010-0068 DRAWN BY: DRWNGKUSATO 2009/07/30 CHECKED BY: CHYKOSHINOYAMA 2009/07/31 APPROVED BY: APPR:KMORI KAWA 2009/07/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±---	DRAWN BY HSHIMOYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER		
	10 OVER 30 UNDER	±---	CHECKED BY HHIRATA	DATE 2005/08/22	MOLEX INCORPORATED		
	30 OVER	±---	APPROVED BY MSASAO	DATE 2005/08/22	DOCUMENT NO. SD-501628-003		
	ANGULAR ±--- °		MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					